

## AEC/APC Symposium Asia 2011

- Join us to make the move to more intelligent manufacturing -  
Wednesday, November 9, 2011  
National Center of Sciences Building, Tokyo, Japan

### AEC/APC Symposium Asia 2011 in Tokyo, Japan

#### Important Date:

July 15  
Extended abstract  
submission due  
Aug. 23  
Notification of abstract  
acceptance  
Oct. 19  
Presentation materials due

In recent years, remarkable achievements have been realized in the field of AEC/APC which can be called the core of scientific semiconductor production technology. It is an important factor holding the key to improving the efficiency of equipment and yield enhancement in leading-edge LSI manufacturing.

Experts will present the results of advanced development in the field of AEC/APC and exchange knowledge and technology. We look forward to receiving additional abstracts and publishing more articles, including proposals for the future.

This call for papers is directed to the semiconductor and photovoltaic community, and other relevant industries, such as display, LED, lamps or glass. Other industries employing AEC/APC may also submit abstracts. The conference, focused on current challenges and future needs beyond AEC/APC, will be built around sessions of the following topics:

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#### Process Level Topics

##### Equipment and Process Control methodology:

Fault detection and classification  
Statistical process control  
Run-to-run control  
Enhanced equipment quality assurance

##### Productivity & Tool Optimizations:

Throughput enhancement  
Uptime ratio improvement  
Cost reduction  
Non-product wafer reduction  
Maintenance

##### Model-based Process Control:

Physical and chemical process model  
Model-based sensors  
Soft sensor  
Virtual metrology  
Sampling plan

##### Tool Data Analysis:

Data collection  
Data acquisition  
Failure and Yield Analysis  
Statistical approaches  
Non-statistical approaches

#### Fab Level Topics

##### Data Analysis, Modeling and Visualization:

Data collection  
Correlation analysis  
Mathematical methods and model creation,  
Novel methods of data visualization and  
Data analysis

##### Control Methods:

Run to run  
Real-time control  
Control algorithms

##### Benefit of APC Application:

CoO  
OEE  
Yield  
Productivity  
Environment, safety and health

##### APC Integration:

Fab automation  
Scheduling and dispatch  
Yield management  
Design for manufacturing  
Supply chain management

##### IT Infrastructure for APC:

Fab-wide APC  
Tool interfaces and communication  
Innovative IT solutions

##### APC Strategy:

Future Needs and opportunities

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#### Online Abstract Submission Procedure:

- Prospective authors are requested to submit the abstract through web browser, consisting of exactly two pages of A4-paper size.
- The first page consists of the text (max of 1,000 words) and the second page consists of figures, supporting data, charts, photos and drawings.
- Only MS Word and JPEG/GIF files are compatible.
- The abstract must be written in English, using the online abstract submission form.
- Submit electronically before July 15, 2011.

Information, templates, and other details are available on the website:  
<http://www.semiconportal.com/AECAPC/cfp.html>

Contact: Semiconductor Portal, Inc.

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